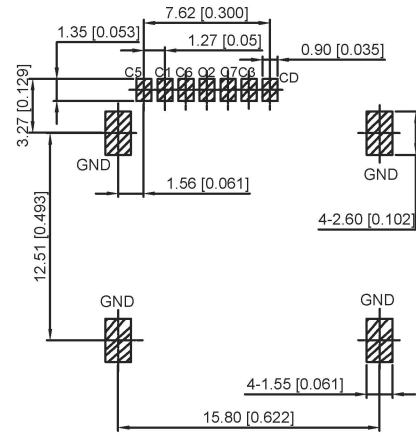
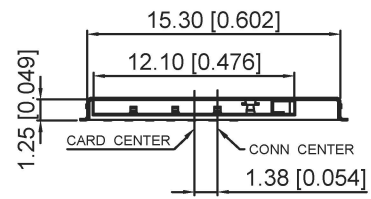
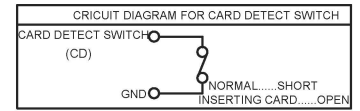
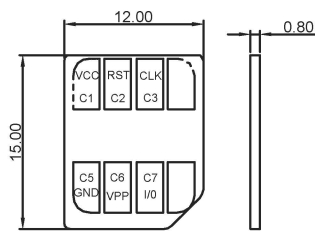


NOTES:
 1)MATERIAL:
 HOUSING: LCP. PLASIC UL 94V-0
 CONTACT: COPPER ALLOY
 SHELL: STAINLESS STEEL
 2)FINISH:
 CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATED ON SOLDER TAILS.
 3)PART NO.:
 XKSMO-003-X
 1:GOLD PLATED G/F



ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	7	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

■ CIRCUT TRACE KEEP OUT AREA
 ■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

广东星坤科技股份有限公司

3FF SIM CARD

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
生					
效					
Δx					
Δx					
Δx					
文件	工程	章			

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	SIM CARD CONN
CHKD	DATE	UNIT: mm/in	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.:
			XKSIM-002-P7
			WEIGHT
			SHEET
			REVISION
			1.0g
			1/1
			A0

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